



PRESS RELEASE

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Heterogeneous Integration Drives New Package Developments

The high cost of moving to the next semiconductor technology node is changing the role of packaging and assembly in the electronics industry. Heterogeneous integration has become the solution to achieve the economic advantages that were previously met with silicon scaling. TechSearch International's new report describes these packaging options, including silicon interposers, fan-out on substrate, and organic solutions such as Intel's EMIB. Homogeneous packaging solutions such as AMD's multichip package are also discussed. The report explains the reason for adoption in each application and provides market projections. A roadmap of future 3D packaging trends is presented and new concepts such as Intel's Foveros are discussed.

Changes in RF package adoption are examined. Antenna-in-Package solutions for 5G are introduced and a market forecast is provided. A special section examines trends in 3D printing, highlighting printed antennas.

The latest Advanced Packaging Update is a 41-page report with full references and an accompanying set of 48 PowerPoint slides.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 18,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887 or see www.techsearchinc.com. Follow us on twitter @Jan_TechSearch